NOT RECOMMENDED FOR NEW DESIGN USE DMP3036SSS

ZXM66P03N8

SO8

D

30V P-CHANNEL ENHANCEMENT MODE MOSFET

SUMMARY

V(BR)DSS=-30V; RDS(ON)=0.025Ω; ID=-7.9A

DESCRIPTION

This new generation of high density MOSFETs from Zetex utilises a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.

FEATURES

- Low on-resistance
- · Fast switching speed
- · Low threshold
- · Low gate drive
- Low profile SOIC package

APPLICATIONS

- DC DC converters
- Power management functions
- Disconnect switches
- Motor control

DEVICE MARKING

ZXM 66P03

ORDERING INFORMATION

REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
7"	12mm	500 units
13"	12mm	2500 units
	7"	7" 12mm

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Top View



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ABSOLUTE MAXIMUM

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DSS}	-30	V
Gate- Source Voltage	V _{GS}	±20	V
Continuous Drain Current V_{GS} =-10V; T_A =25°C(b) V_{GS} =-10V; T_A =70°C(b) V_{GS} =-10V; T_A =25°C(a)	۱ _D	-7.9 -6.3 -6.25	A
Pulsed Drain Current (c)	IDM	-28	A
Continuous Source Current (Body Diode)(b)	۱ _S	-4.1	A
Pulsed Source Current (Body Diode)(c)	ISM	-28	A
Power Dissipation at T _A =25°C (a) Linear Derating Factor	PD	1.56 12.5	W mW/°C
Power Dissipation at T _A =25°C (b) Linear Derating Factor	PD	2.5 20	W mW/°C
Operating and Storage Temperature Range	Tj:Tstg	-55 to +150	°C

THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	R _{0JA}	80	°C/W
Junction to Ambient (b)	R _{0JA}	50	°C/W

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NOTES

(a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions
(b) For a device surface mounted on FR4 PCB measured at t \$10 secs.
(c) Repetitive rating 25mm x 25mm FR4 PCB, D = 0.05, pulse width 101-s - pulse width limited by maximum junction temperature.



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PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS	
STATIC	•					1	
Drain-Source Breakdown Voltage	V(BR)DSS	-30			V	I _D =-250µA, V _{GS} =0V	
Zero Gate Voltage Drain Current	IDSS			-1	μA	V _{DS} =-24V, V _{GS} =0V	
Gate-Body Leakage	IGSS			-100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$	
Gate-Source Threshold Voltage	V _{GS(th)}	-1.0			V	I _D =-250µA, V _{DS} = V _{GS}	
Static Drain-Source On-State Resistance (1)	R _{DS(on)}			0.025 0.035	Ω Ω	V _{GS} =-10V, I _D =-5.6A V _{GS} =-4.5V, I _D =-2.8A	
Forward Transconductance (1)(3)	9fs		14.4		S	V _{DS} =-15V,I _D =-5.6A	
DYNAMIC (3)	·		•			·	
Input Capacitance	C _{iss}		1979		pF	V _{DS} =-25 V, V _{GS} =0V, f=1MHz	
Output Capacitance	C _{oss}		743		pF		
Reverse Transfer Capacitance	C _{rss}		279		pF		
SWITCHING(2) (3)							
Turn-On Delay Time	^t d(on)		7.6		ns	V _{DD} =-15V, I _D =-5.6A	
Rise Time	tr		16.3		ns		
Turn-Off Delay Time	^t d(off)		94.6		ns	R _G =6.2Ω, V _{GS} =-10V	
Fall Time	tf		39.6		ns		
Gate Charge	Qg		36		nC	V _{DS} =-15V,V _{GS} =-5V I _D =-5.6A	
Total Gate Charge	Qg		62.5		nC	-V _{DS} =-15V,V _{GS} =-10V -I _D =-5.6A	
Gate-Source Charge	Qgs		4.9		nC		
Gate Drain Charge	Q _{gd}		19.6		nC		
SOURCE-DRAIN DIODE	I		1	1	1	1	
Diode Forward Voltage (1)	V _{SD}			-0.95	V	T _j =25°C, I _S =-5.6A, V _{GS} =0V	
Reverse Recovery Time (3)	t _{rr}		35		ns	Tj=25°C, IF=-5.6A, di/dt= 100A/µs	
Reverse Recovery Charge(3)	Q _{rr}		39.9		nC		

ELECTRICAL CHARACTERISTICS (at Tamb = 25°C unless otherwise stated).

(1) Measured under pulsed conditions. Width=300 $\mu s.$ Duty cycle ${\leq}2\%$.

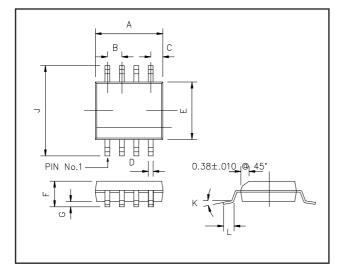
(2) Switching characteristics are independent of operating junction temperature.

(3) For design aid only, not subject to production testing.



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PACKAGE DIMENSIONS



DIM	Millimetres		Inches		
	Min	Max	Min	Max	
А	4.80	4.98	0.189	0.196	
В	1.27 BSC		0.05 BSC		
С	0.53 REF		0.02 REF		
D	0.36	0.46	0.014	0.018	
E	3.81	3.99	0.15	0.157	
F	1.35	1.75	0.05	0.07	
G	0.10	0.25	0.004	0.010	
J	5.80	6.20	0.23	0.24	
К	0°	8°	0°	8°	
L	0.41	1.27	0.016	0.050	

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